

ABSTRACT OF THE DISCLOSURE

The present invention is directed to an inter-laminar adhesive composition containing a liquid epoxy resin, a polyfunctional epoxy resin having a softening point higher than a lamination temperature of the adhesive and with two or more epoxy groups within the molecule; and a latent epoxy curing agent initiating a reaction at a temperature higher than the lamination temperature. The adhesive composition optionally contains a liquid resin other than the liquid epoxy resin and/or an organic solvent and the liquid resin includes the liquid epoxy resin, the organic solvent or both constituting from 10 to 55% by weight of the composition.

This inter-laminar adhesive composition allows for the preparation of a multi-layer printed wiring board. The process for preparing the multi-layer printed wiring board is provided. The resulting multi-layer printed wiring board of the invention possesses excellent embedding properties in the internal-layer circuit, excellent surface smoothness and can be provided at high productivity levels in a building up process using the present adhesive.

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